

Electronic Patent Application Fee Transmittal

Application Number:	10541586			
Filing Date:	30-Sep-2005			
Title of Invention:	Curing resin composition, adhesive epoxy resin paste, adhesive epoxy resin sheet, conductive connection paste, conductive connection sheet, and electronic component joined body			
First Named Inventor/Applicant Name:	Koji Watanabe			
Filer:	Burton A. Amernick/Mary Ann Taylor			
Attorney Docket Number:	21581-00456-US			
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Submission- Information Disclosure Stmt	1806	1	180	180
Total in USD (\$)				180